VLA TECHNICAL REPORT #4

MODULES T4A and T4B LO OFFSET

A. R. Thompson

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- I. Related Material Not Included in the Manual
  - (a) Drawings and Parts Lists
  - (b) Publications and Memoranda
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- IV. Bills of Materials
- V. Data Sheets and Specifications MlJ

Specification A13450N1

Avantek UTO Modules

#### FIGURES

1. Schematic Diagram of L.O. Offset Module

I (a). L.O. OFFSET MODULE (T4A & T4B), DRAWINGS AND PARTS LISTS

### Schematic Diagram

L.O. Offset Schematic

## Parts List

L.O. Offset Module

## Module, Mechanical

Front Panel Rear Panel Top and Bottom Support Bar Left Side Plate Perforated Cover Fastener for Perforated Cover Guide Mixer Mounting Blocks Assembly Drawing for L.O. Offset Module C13450S2

### A1345024

B13450M21 (Parts 1&2) B13450M20 B13050M3 C13450M22 C13050M7 C13050M17 B13050M4 A13050M33 D13450P5

I (b). RELATED PUBLICATIONS AND MEMORANDA

VLA Electronics Memo #116

Some Tolerances Relating to Spurious Responses A. R. Thompson August 29, 1973

Addendum to VLA Electronics Memo #116 A. R. Thompson September 6, 1973

## II. Operation and Circuit Description

The LO Offset module provides the oscillator signals for converting the IF signals from the modem down to base-band. This conversion is performed in the IF Receiver modules. The IF bands are 1300-1350, 1400-1450, 1550-1600, and 1650-1700 MHz, and when using the full bandwidths of the IF Receiver modules the required LO frequencies are 1300, 1400, 1550, and 1650 MHz. When using the narrower IF Receiver bandwidths it is necessary to be able to select the signal from any part of the 50 MHz wide band, and this requires that the four LO frequencies also be variable over +25 MHz.

In transmission along the waveguide the 1300-1350 and 1400-1450 MHz signals effectively become sidebands to a 1200 MHz subcarrier, and hence share with that signal some of the instrumental phase shifts that may occur in the transmission. To remove these unwanted phase shifts the received 1200 MHz signal is subtracted from the two IF bands by deriving the local oscillator for the IF Receivers from the same 1200 MHz. This is done in an LO Offset module, the circuit of which is shown in Figure 1. The 1200 MHz input at J1 is divided in a power splitter and fed into two mixers. The mixers also receive signals at 100  $\pm$ 25 MHz from J2 and 200  $\pm$ 25 MHz from J4. The sum frequencies are selected by appropriate filters F1 and F2 and the outputs at 1300  $\pm$ 25 MHz and 1200  $\pm$ 25 MHz are amplified and appear at J3 and J5. These outputs go to the L0 inputs of two IF Receiver modules. The amplifiers, Avantek ASD 8199M, were supplied in accordance with specification no. Al3450N1 and contain one each UT02011, UT02002 and UT02003 module (see Section V.)

In an exactly similar way, the IF bands at 1550-1600 and 1650-1700 MHz act as sidebands on an 1800 MHz subcarrier in the waveguide transmission. The LO signals for these channels are derived by subtracting  $250 \pm 25$  MHz and  $150 \pm 25$  MHz from 1800 MHz in another LO Offset module. The LO Offset module



BANDBASS FILTER TABLE - 10000 m

14	A MODULE She input )	(1.6 GHZ INPUT)			
ALTER	DESCRIPTION	FILTER	Description		
FL1	68:20-1300/100-0	EL 3	68120+1550/100-0 KEL		
FL2	68120-1400/100-0	FL4	68120-1950/100-0		

INPUT & OUTPUT	FREQUENCIES	AND PON	ma levels
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теям.	TAA MODULE	T48 MODULE	COMMON Power Levels
JI	1200 MH2	1800 MHE	8.5 ± 1,5 dbm
JZ	100 125 MH2	250 \$ 25 MH	-10 dbm
JB	1300 1 25 MHZ	1550 125 MHZ	8±4 dbm
J4	200 ± 25 MHZ	150 ± 25 MHZ	-10 dbm
JB	1400 ± 25 MHE	1650 ± 25 MH	8±4 dbm



which produces the two lower LO signals is designated T4A and the one which produces the two higher frequency signals T4B. The T4A and T4B modules differ only in the center frequencies of the filters F1 and F2 as shown in Figure 1.

In the central control building the equipment that receives the signals from each antenna is called the IF Receiver sybsystem. It contains one T4A and one T4B module which together produce the LO signals for 4 IF Receiver modules. The T4A and T4B modules are located in slots 1 and 2 respectively of bin S, rack N.

The LO Offset module is so simple that test procedures are rather obvious. A signal at 1200 or 1800 MHz is injected at Jl and a signal variable over the appropriate frequency range at J2 or J4. The output at J3 or J5 is best displayed on a spectrum analyzer, so that as well as checking that the wanted frequencies are present at the correct level, the presence of any unwanted signals can also be detected. For a correctly operating module, avoidance of unwanted responses is the main constraint on the input power levels, as discussed in the following section.

Power requirements for each T4A and T4B module are 140 ma at +15V. III. Spurious Responses

Let  $f_1$  indicate the frequency 1200 or 1800 MHz entering Jl and  $f_2$  denote the frequency entering J3 or J4. The spurious responses with which we are concerned are of two kinds. The first occurs when  $2f_1 - mf_2$  falls within the passband of the appropriate filter Fl or F2. The second occurs when  $nf_2$  falls within the filter passband. Here m and n are integers, and both responses depend upon the production of harmonics of  $f_2$  within the mixer. The strengths of these harmonics fall off as the harmonic number m or n increases, and thus the most serious unwanted signals are expected when m or n have the lowest value. Note that the two kinds of responses can be identified on the spectrum analyzer

by watching how much they increase or decrease in frequency for a given change in  $f_2$ .

The lowest troublesome harmonic turns out to be the fifth, and it results in a spurious response of the first kind which occurs in the second highest LO channel;  $2 \ge 1200 - 5 \ge 200 = 1400$  MHz. Measurements on modules (Serial Number Al of both T4A and T4B types) confirm that this is the strongest unwanted response. The level of this response relative to the wanted output depends upon the input levels of  $f_1$  and  $f_2$ . The relative strength of the unwanted response decreases as  $f_2$  is decreased, but we cannot make  $f_2$  much less than -10 dBm unless a higher gain output amplifier is used to compensate for loss in strength of the required output. With  $f_2$  at a level of -10 dBm the unwanted response was found to be a minimum when the 1200 MHz level at J1 was 8.5 dBm, and for a range of levels between 7 and 10 dBm the unwanted response was 65 dB below the wanted output.

What is the maximum tolerable level of the spurious response? The discussion in VLA EM #116 (see case (G) on pp.6-7) plus the addendum to that memorandum indicates that the resulting signal in the IF should be 62 dB below the total IF signal in the 50 MHz bandwidth. The IF level at the mixer inputs of the IF receivers is approximately -20 dBm, so the maximum tolerable strength for an unwanted signal is -82 dBm at the signal input of the mixer or -57 dBm at the LO input, taking the RF-LO isolation as 25 dB. The -57 dBm level is -65 dB relative to the wanted LO signal. Thus the observed level of -65 dB should be just about tolerable. If further suppression is found to be necessary, reduction of the  $f_2$  level would be a possible approach.

For the second kind of spurious response the lowest harmonic that will be encountered is the seventh;  $7 \times 200 p = 1400$  MHz. Measurements indicate that this response is about 10 dB below the one discussed above. Unwanted responses in the other three LO frequency channels were all found to be of negligible level.

The required input power levels to the module are summarized in the table in Figure 1. The levels at J2 and J4 should not exceed the -10 dBm figure by more than one or two dBm but can be lower so long as sufficient output is obtained at J3 and J5. The output levels given,  $8 \pm 4$  dBm, represent the tolerable range of input power at the mixers in the IF Receiver modules.

XX ELECTRICAL	MECHAN	NICAL BOM #	A13450Z4	rev <u>B</u>	DATE	PAG	E <u>1</u> C	)F
MODULE #	NAME L.O. Offs	et .	DWG #	450P5 SUB	ASMB		DWG #	19-19-19-19-19-19-19-19-19-19-19-19-19-1
SCHEMATIC DWG #	C13450S2 LC	CATION	QUA/S	YSTEM	PREPARED BY	J. Gray	APPROVED	Have

ITEM	REF	MANUFACTURER	MFG PART #	DESCRIPTION	TOTAL	QUANT.
	DESIG				-T4A	T4B
1		N.R.A.O.		L.O. Offset Ass'y.		
2		Omni-Spectra	20493	Isolated Power Divider	1	1
3						-
4		11 II	OSM 218	Straight R.F. Adapter	2	2
5		11 I)	OSM 201-1A	" R.F. Connector	13	13
6	Jl thru J5	11 13	омозо43-75	R.F. Connector	5	5
7		Avantek	ASD-8199M	1-2 GHz Amp	2	2
8						
9		K&L Microwave, Inc.		Filter Clips	4	4
10		Relcon	MlJ	Mixer	2	2
11		AMP Special Industries	201355-3	Connector, 14 Pin	1	1
12		13 NI 11	201347-4	Connector Shield	1	1
13		ar ar 11	202512-1	Ground Guide Socket	1	1
14		11 FI TI	202514-1	Guide Pin	1	1
15		<u>n u o</u>	201578-1	Crimp Pins	2	2

XX ELECTRICAL	MECHANICAL	BOM # A13450Z4	rev <u>B</u>	DATE	PAGE 2	OF4
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ITEM	REF	MANUFACTURER	MFG PART #	DESCRIPTION		QUANT.
#	DESIG				T4A	T4B
16		Uniform Tubes	UT 141	R.F. Cable, 8 ft.	1	1
17			#24 AWG, B1k.	Wire, Multi-Strand, PVC Insul.	1	1 ft
18			#24 AWG, Rd.	""""""""""""""""""""""""""""""""""""""	1	1
19				Solder	A/R	A/R
20		K&L Microwave	6B120 1300/100-0	Filter T4A	1.	
21		K&L Microwave	6B120-1400/100-0	Filter "	1	
22	-	K&L Microwave	6B120-1550/100-0	Filter T4B		1
23		K7L Microwave	6B120-1650/100-0	Filter "		1
24		Panduit	SST 1M	WIRE TIE	2	2
25						
26						
27						
28 .						
29						
30						
31						
32						

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ELECT	RICAL	XX MECHANICAL BOM	A13450Z4 REV	3 DATE PAGE	OF4	1
ITEM #	REF	MANUFACTURER	MFG PART #	DESCRIPTION	TOTAL	QUANT.
33		N.R.A.O.	C13450M22	Lt. Side Plt.	1	
34						
35 <sup>-</sup>		li	B13450M20	Panel, Rear	1	1
36			B13050M3	Bar, Support, Top & Bottom	2	2
37			C13050M7	Top Cover	1	l
38			B13050M17	Fastener, Perf. Cover	2	2
39		11	B13050M4	Guide, Module	2	2
40		Southco	47-11-204-10	Screw, Captive	2	2
41			#6-32×.625	St. St'l. Pan. Hd. Slotted	2	2
42			#6-32x.750	11 1J II 11 11	2	2
43			#6-32x.250	" " Hex Soc. Cap. Scr.	2	2
44			#6-32x.250	St. St'l. Pan Hd. Scr.	4	4
45		an fe sea de la calendar de la calen	#6-32x.250	St. St'l. Flat Hd. Scr.	12	12
46			#4-40x.312	11 <sup>-</sup> 17 13 11 11	4	4
47			#4-40x.250	St. St'l. Flat Hd. Scr.	8	8
48	1		#4-40x.500	11 17 17 11 11	4	4
49	-		#2-56x1.00	rt 17 U 17 Tł	2	2

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لابابلابلالا ا	KICAL	$\Lambda \Lambda$	LIDCUMMICAD	MIJ4J024	T/m A					-	

ITEM	REF	MANUFACTURER	MFG PART #	DESCRIPTION	TOTAL	QUANT.
#	DESIG		· · · · · · · · · · · · · · · · · · ·		74A	74B
50			#4-40	Hex Nut, St. St'l.	8	8
51			#4	Washer, Flat	8	8
52			<b>#2-</b> 56	Hex Nut, St. St'l.	2	2
53			#6	Washer, Flat	4	4
54		NRAO	<b>B</b> 13050M33	Mixer support	4	4
55 ·		NRAO	B13450M20-1	Panel, Front	1	
56			B13450M21-2	'n 1)		1
57						
58						
59						
60		· · · ·				
61						
62						
63						
64						
65		= =				
66	-					



DC TO 2.0 GHz DOUBLE-BALANCED MIXER MODEL M1J

- HIGH ISOLATION: >50 dB (TYP.)
- LOW NOISE FIGURE: 6 dB (TYP.)
- WIDE-BAND IF: DC to 1.0 GHz
- HERMETICALLY SEALED

Introduction The Model M1J is a wide-band double-balanced mixer in a hermetically sealed package. This mixer is designed to provide maximum isolation of the local oscillator (LO) signal for best possible suppression of internally generated harmonics and LO leakage. It is also designed for a low noise figure.

Mixing When two signals are fed to the mixer, sum and difference frequencies are produced at the third port. Best isolation is achieved by feeding the high-level LO signal to the L-port. Both L- and Rports are ac-coupled and have a 0.3 to 2.0 GHz frequency response. The I-port is dc-coupled and has dc to 1 GHz frequency response. For downconverting applications, feed the input signal into the R-port and take the output from the I-port. For up-converting applications, feed the input signal into the l-port and take the output from the R-port. Minimum conversion loss is achieved by providing a LO level of +7 dBm or greater. At this level, conversion loss is typically 6 dB for an IF frequency less than 200 MHz. For minimum intermodulation products, the input signal level should be as low as possible.

Pulse Modulation For best modulation performance, feed the unmodulated signal to the L-port and the modulating signal to the I-port. An unlimited pulse length is possible as the I-port is direct coupled. Reversal of the modulating signal's polarity will allow the output to be shifted by 180 degrees. A modulating signal level of 20 mA will minimize insertion loss. As the mixer is constructed with Schottky Barrier diodes, rise and fall times less than 1 nsec. can be achieved.

Amplitude Modulation To amplitude modulate, insert a dc off-set current along with the modulating signal at the I-port. The carrier signal is inserted at the L-port and the modulated signal is taken from the R-port. The dc-current controls the amount of carrier present in the output.

Phase Detection The mixer's excellent balance eliminates null balance adjustments and minimizes interaction between the signal sources. With identical frequencies fed to the R- and L-ports, a dc-output related to the phase difference between the two signals will appear at the I-port. A maximum positive dc-output indicates the signals are in phase; zero dc-output indicates the signals are separated by 90 degress; and, a maximum negative dc-output indicates the signals are 180 degrees out of phase.

Current-Controlled Attenuation In this mode of operation, a dc-current into the I-port determines the amount of signal passed from the L-port to the R-port. Maximum attenuation, corresponding to the mixer's isolation, is achieved with no dccurrent. Minimum attenuation is achieved with dc-current equal to, or greater than, 20 mA.

Note: Avoid damage to the mixer diodes by always driving the I-port with a current-limited source.

## WATKINS-JOHNSON COMPANY

3333 Hillview Avenue, Palo Alto, California 94304 (415) 493-4141, TWX: 910-373-1253, TELEX: 348-415, CABLE: WJPLA **FEBRUARY 1973** 



# MODEL M1J SPECIFICATIONS\*

	7.0 dB 8.5 dB	fL & f <sub>R</sub> 1000 to 1800 MHz f <sub>I</sub> DC to 200 MHz f <sub>I</sub> 200 to 1000 MHz
	8.0 dB 9.0 dB	f <sub>L</sub> & f <sub>R</sub> 300 to 2000 MHz f <sub>1</sub> DC to 200 MHz f <sub>1</sub> 200 to 1000 MHz
	7.0 dB 8.5 dB 8.0 dB 9.0 dB	$\begin{array}{c} f_L \ \& \ f_R \\ 1000 \ to \ 1800 \ MHz \\ f_1 \ 10 \ to \ 200 \ MHz \\ f_1 \ 200 \ to \ 1000 \ MHz \\ \hline f_L \ \& \ f_R \\ 300 \ to \ 2000 \ MHz \\ f_1 \ 10 \ to \ 200 \ MHz \\ f_1 \ 200 \ to \ 1000 \ MHz \end{array}$
40 dB 25 dB 20 dB 35 dB 25 dB 20 dB	} 	f <sub>L</sub> 300 to 1000 MHz f <sub>R</sub> 300 to 1000 MHz f <sub>L</sub> 1000 to 2000 MHz f <sub>R</sub> 1000 to 2000 MHz
	1.0 dB	f <sub>R</sub> level = 0 dBm
	1.0 dB	f <sub>R2</sub> level = -2 dBm
	40 dB 25 dB 20 dB 35 dB 25 dB 20 dB	8.5 dB 8.0 dB 9.0 dB 7.0 dB 8.5 dB 8.0 dB 9.0 dB 9.0 dB 1.0 dB 1.0 dB 1.0 dB

## SCHEMATIC DIAGRAM



## **ABSOLUTE MAXIMUM RATINGS**

Storage Temperature	65°C to +100°C
Operating Temperature	54°C to +100°C
Peak Input Power	400 mW max. at 25°C
	Derate to 50 mW at
	100°C (4.67 mW/°C)
Peak Input Current	50 mA

## **ENVIRONMENTAL**

The Model M1J Mixer will meet its specifications over the temperature range of  $-54^{\circ}$ C to  $+100^{\circ}$ C and after exposure to any or all of the following tests per M1L-STD-202D:

Exposure	Method	<b>Test Condition</b>
Thermal Shock	107C	В
Altitude	105C	G
H.F. Vibration	204B	Ď
Mechanical Shock	213A	С
Random Vibration (15 minute per axis)	214	11F
Humidity	106C	
Temperature Cycle	102A	С

The M1J will meet the environmental requirements of M1L-E-16400F, Class 1 and M1L-E-5400L Class 2.

WEIGHT	31 grams (1.1 oz.) maximum
CONNECTORS	SMA
WARRANTY	1 Year

## OUTLINE DRAWING



NOTE: DIMENSIONS ARE IN INCHES

**Mixer Test Circuit:** When terminated as shown, the mixer impedance at the R- and I-ports is 50 ohms. The impedance at the L-port is nonlinear and is a function of the  $f_L$  level. For most applications, the  $f_L$  level should be as shown. This is equivalent to delivering 5 milliwatts (+7 dBm) into a 50-ohm load. The  $f_R$  level should be below 1 milliwatt (0 dBm) in order to avoid conversion compression.



Drive Level: The minimum recommended drive level is +4 dBm. This level has been established on the premise that a lower drive level will degrade the conversion loss and noise figure over the full temperature and frequency range. Operation at +4 dBm is recommended to reduce the level of the intermodulation products in the lower two rows of the intermodulation chart. It will also minimize the output noise below 2 kHz.

The maximum recommended drive level is +13 dBm. This upper level has been established by the desire to avoid a serious increase in noise figure and a loss of isolation. Operation at +13 dBm is recommended to achieve best two-tone performance and best suppression of the intermodulation products in the rows above the second row in the intermodulation chart.



**Conversion Loss vs. Input Frequency:** Conversion loss of the mixer when used in an SSB system. The frequency ordinate refers to the R-port ( $f_R$ ) with  $f_1$  at 150 MHz. Data plotted with an  $f_L$  level of +7 dBm.



**Conversion Loss vs.**  $f_I$  Frequency: Conversion loss of the mixer when used in a SSB system. The frequency ordinate refers to the I-port ( $f_I$ ) with  $f_R$  at 1200 MHz and  $f_L$  swept from 200 to 1100 MHz.



Isolation vs. Frequency: Level of the  $f_L$  signal fed through to the R- and I-ports with respect to the level of the  $f_L$  signal at the L-port.



## TYPICAL PERFORMANCE AT 25°C (Con't.)

VSWR vs. Frequency: VSWR of the L-, I- and R-ports in a 50-ohm system with  $f_L$  at +7 dBm. Some variation in the R-port VSWR will occur as a function of the L-port frequency. Curves for the R-port VSWR are plotted for L-port frequencies of 0.6 and 1.6 GHz. Also shown are the L-port VSWR and the I-port VSWR with  $f_L$  at 0.6 GHz.



Harmonic Intermodulation Products: Intermodulation signals which result from the mixing of mixer generated harmonics of the input signals are shown below. Mixing product suppression is indicated by the number of dB below the desired output level,  $f_R$ - $f_L$ . Products are for the difference frequencies  $nf_L$ - $mf_R$  and  $mf_R$ - $nf_L$ . The performance was measured with  $f_R$  at 300 MHz, -10 dBm;  $f_L$  = 299 MHz, +7 dBm for light area and +13 dBm for shaded area.



# Thin Film Unit Amplifiers—MICoamp® Modules



MIC•amps

## ARRANGEMENT OF MODULES FOR SYSTEMS USE

In a normal cascade, UTO Series modules are arranged in ascending order, according to output power, to achieve the desired level of gain. UTF Series attenuators can be placed in cascade for the purpose of gain control. Their position in the cascade of amplifier modules is determined by the user's dynamic range and noise figure requirements.

#### **BONUS FEATURE**

Up to three of most of the MIC-amp substrates may be cascaded within the new miniature Dual-In-Line (DIP).

## THIN FILM ATTENUATORS (TO-8 Package)



This package provides the smallest "connectorless" hermetic configuration (see page 14).

	Frequency	Insertion Loss	Attenuation		Control Power		Inpu	Input Power	
Mod <del>el</del>	Range	(dB)	(dB)	VSWR	Volts DC	Current mA	Volts	Current mA	
	(MHz)	Maximum	Minimum	Maximum	(Typical	(Typical)	DC	(Typical)	
UTF-015	5-1000	2.5	15	2.0	-10	7	+15	7	
UTF-040	5-1000	2.5	30 <sup>1</sup>	2.0	-10	45	+15	10	
UTF-2015	500-2000	2.5	15	2.0	-10	7	+15	7	

<sup>1</sup>35 dB min, 10-500 MHz; 40 dB min, 20-250 MHz

							Power Output	Typical		
	Frequency			Noise	vs	WR	For 1 dB	Intercept	Inna	t Power
	Response	Gain	Flatness	Figure	(50 c	ohms)	Gain Compressio	on Point For	(±1% E	Regulation
	(MHz)	(d8)	(±d8)	(dB)	Max	imum	(dBm)	IM Products	Volts	Cucreat m.
Niodel	Minimum	Minimum	Maximum	Maximum	In	Out	Minimum	(dBm)	DC	(Typical)
UTL-502	5-500	7	1.0	11	2.0	2.0	(Sat Power)	Even harmonics	+15	15
	Limiting	Small					-4 dBm (min)	15 dB down		
	Amplifier	Signal					-2 dBm (typ)	w/input from	-15	15
	-							-50 to +7 dBm		
UTO-510	5-500	15	1.0	3.0	2.0	2.0	-2	+8	+15	10
UTO-511	5-500	15	1.0	2.5	2.0	2.0	-2	+8	+15	10
UTO-501	5-500	14	1.0	4.0	2.0	2.0	-2	+11	+15	10
UTO-502	5-500	14	1.0	5.5	2.0	2.0	+7	+21	+15	23
UTO-503	5-500	9.0	1.0	7.0	2.0	2.0	+13	+27	+24	50
UTO-504	5-500	6.0	1.0	11	2.0	2.0	+17	+31	+24	100
UTO-512	5-500	20	1.0	4.5	2.0	2.0	+7	+20	+15	23
UTO-513	5-500	16	1.0	6.0	2.0	2.0	+14	+36 even	+24	50
							~ -	+27 odd		
UTO-521	5-500	27	1.0	5.5	2.0	2.0	+6	+18	+15	38
UTO-523	5-500	23	1.0	7.0	2.0	2.0	+12	+36 even	+15	80
							· <u>·</u>	+25 odd	_	
010-551	5-500	15	1.0	4.0	2.0	2.0	-5	+10	+5	7
UTO-1001	5-1000	14	1.0	5.0	2.0	2.0	-2	+11	+15	·10
UTO-1002	5-1000	14	1.0	6.5	2.0	2.0	+7	+21	+15	23
UTO-1003	5-1000	9.0	1.0	8.0	2.0	2.0	+13	+27	+24	50
UTO-1051	5-1000	10	1.0	5.0	2.0	2.0	-5	+10	+5	7
UTO-1511	5-1500	10	0.5	4.5	2.0	2.0	-9	+1	+15	7
UTO-1501	5-1500	9.0	0.5	5.5	2.0	2.0	-3	+10	+15	10
UTO-1502	5-1500	9.0	0.5	7.5	2.0	2.0	+6	+19	+15	23
UTO-1503	5-1500	6.0	0.5	9.0	2.0	2.0	+12	+25	+24	50
UTO-2011	1000-2000	7.5	0.5	5.0	2.0	2.0	-3	+10	+15	12.5
UTO-2001	1000-2000	7.5	0.5	6.0	2.0	2.0	-3	+10	+15	12.5
UTO-2002	1000-2000	8.0	0.5	7.0	2.0	2.0	+3	+16	+15	20
UTO-2003	1000-2000	8.0	0.5	8.0	2.0	2.0	+7	+20	+15	30
UTO-2311	1700-2300	8.0	0.5	5.0	2.0	2.0	-3	+10	+15	15
UTO-2302	1700-2300	8.0	0.5	6.5	2.0	2.0	+3	+13	+15	18
UTO-2303	1700-2300	8.0	0.5	8.0	2.0	2.0	+10	+20	+15	30

## UTO "R" SERIES

The UTO "R" Series MIC-amps offer all the circuit performance advantages and specifications of their counterparts, the standard, premium commercial grade UTO. In addition, each of the "R" Series MIC-amps has been screened in accordance with MIL-STD-883 procedures. Reliability, therefore, is established and MTBF (in accordance with the criteria of MIL-HDBK-217A) is predicted to be in excess of ten million hours at 25°C.

		·	MIL-STD-883		
	TEST	CONDUCIONS	METHOD	CONDITIONS	
1.	Precap Visual	Sae Note 1			
2.	Preseal Bake	2 hrs, min. at 150°C		· · ·	
3.	Seal				
4.	Stabilization Bake	24 hrs at 125°C	1008	В	
5.	Temperature Cycling	10 cycles	1010	В	
6.	Centrifuge	Y <sub>1</sub> , direction only; 20,000 G's	2001	D	
7.	Fine Leak		1014	A (5 x 10 <sup>-8</sup> cc/sec max)	
8.	Gross Leak		1014	C (Step 1)	
9.	Burn-In	168 hrs	1015	Note 2	
10.	Final Electrical	Go-No-Go at 25°C	Note 3		
11.	External Visual		2009		

Each UTO "R" Series unit is screened 100% to the Class B level assurance tests included in the following:

NOTES: <sup>1</sup> Internal Visual (Precap): Consistent with the intent of Method 2010, MIL-STD-883, as applicable to UTO MIC-amp fabrication techniques. Specific visual inspection criteria applied are described in Avantek's Quality Assurance Standard Workmanship Manual, Section XVI.

<sup>2</sup>See specific UTO "R" Series specifications for burn in temperature and bias conditions.

<sup>3</sup>See specific UTO specification for test conditions and limits.

It is important to realize that both the commercial grade and "R" Series UTO-MIC-amps are manufactured on the same production line. The "R" Series receives the additional screening process described above. Therefore, the commercial grade UTO will also demonstrate a very high degree of reliability. (M.T.B.F. of one million hours is predicted from MIL-HDBK-217A). The augmenting screening procedures of the "R" Series adds the final degree of confidence to the UTO product line when high reliability becomes imperative.

NOTE: All UTO models and specifications listed on the previous page are available in "R" Series versions.

## **CASCADING MIC**•amps

The patented circuit design of the MIC-amp permits cascading of units to achieve added gains.

The MIC•amps may be cascaded in 50 ohm microstrip systems using printed circuits. Also, special hardware is available from Avantek for mounting one to four MIC• amps in aluminum cases to provide a complete, shielded amplifier. Also up to three of most of the MIC•amp sapphire substrated modules may be cascaded in the new Avantek Dual-In-Line (DIP) package (see page 14).

The complete accessory package, which includes an aluminum case, RF connectors and a DC feed-through filter. may be ordered. The printed circuit boards and the MIC-amps are specified separately. Detailed installation instructions are supplied with each unit. TC case dimensions are 0.84" high, 1.5" wide (mounting plate), and length, TC-2, 1.37"; TC-4, 2.4" plus connectors.

Amplifier assemblies may be ordered with MIC-amps installed in the aluminum cases by factory technicians.

Test data consisting of noise figure, gain, VSWR, and power output measurements over the specified bandwidth will be provided with each amplifier assembly.

Expected typical operating performance of MIC-amp cascades are derived from the simple rules shown below. Complete amplifier cascades of up to four modules assembled at the factory will typically meet the specifications listed below:

- Frequency Units are available for operation over various frequency ranges from 5 to 2000 MHz. Minimum band-width is established by the specification of the most narrow member of the cascade.
- Gain Minimum cascade gain is the sum of minimum unit gains.
- Gain Flatness Cascaded flatness will typically be less than the sum of individual module flatness specifications. The individual module data sheets show the very low actual typical module flatness.
- Noise Figure The cascaded noise figure in the TC-cases will be about 1/2 dB greater than that of the input MIC•amp noise figure due to the second stage noise contribution and some connector and TB-board losses at higher frequencies.
- Power Output at 1 dB Gain Compression Point Typical cascade output power is 1 dB less than that of the lowest module output with all modules referred to the output of the cascade.
- VSWR VSWR's of cascades will not exceed 2.5:1. Most VSWR's will be less than 2.0:1.

NOTE: The information listed above applies to cascades of four units or less. For performance information on larger cascades, consult factory.

## NATIONAL RADIO ASTRONOMY OBSERVATORY Charlottesville, Virginia VERY LARGE ARRAY PROJECT

SPECIFICATION NO: A13450N1
NAME: Solid State Amplifier
DATE: February 5, 1974 PREPARED BY: D.K. Marin APPPROVED BY: D. CO.
1. FREQUENCY RANGE: 1.0-2.0 GHz
2. GAIN: 23.5-30 dB (gain of individual units of given type to be equal within +1 dB).
3. GAIN FLATNESS: +1 dB
4. POWER OUTPUT: +7 dBm minimum at 1 dB compression
5. NOISE FIGURE: 6 dB max.
6. VSWR: 2.0 max. (input and output)
7. GATING SPEED: The amplifier must switch on or off in less than 10 microseconds when the power supply voltage is gated on and off. Switching time is defined as rise or fall time from 10% to 90% of final RF power. Insertion loss should be greater than 13 dB from 1 to 2 GHz when gated off.
8. INPUT POWER: +15V
9. CONNECTORS: SMA Female
10. Manufacturer is to state whether unit is discrete component construction and
whether it is reparable in the event of a transistor failure.